

OMITW

SBOS161A - JANUARY 1989 - REVISED JULY 2003

# Precision Dual *Difet* ® Operational Amplifier

#### **FEATURES**

◆ Very Low Noise: 8nV/√Hz at 10kHz

Low V<sub>os</sub>: 1mV max
 Low Drift: 10µV/°C max
 Low I<sub>n</sub>: 10pA max

● Fast Settling Time: 2µs to 0.01%

Unity-Gain Stable

## **APPLICATIONS**

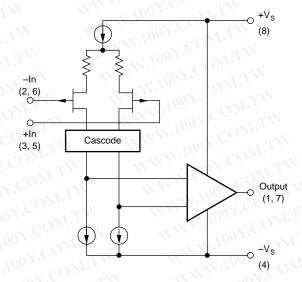
- Data Acquisition
- DAC Output Amplifiers
- Optoelectronics
- High-Impedance Sensor Amps
- High-Performance Audio Circuitry
- Medical Equipment, CT Scanners

#### DESCRIPTION

The OPA2107 dual operational amplifier provides precision **Difet** performance with the cost and space savings of a dual op amp. It is useful in a wide range of precision and low-noise analog circuitry and can be used to upgrade the performance of designs currently using BIFET® type amplifiers.

The OPA2107 is fabricated on a proprietary dielectrically isolated (*Difet*) process. This holds input bias currents to very low levels without sacrificing other important parameters, such as input offset voltage, drift and noise. Laser-trimmed input circuitry yields excellent dc performance. Superior dynamic performance is achieved, yet quiescent current is held to under 2.5mA per amplifier. The OPA2107 is unity-gain stable.

The OPA2107 is available in DIP-8 and SO-8 packages.



勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www.100y.com.tw



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

All trademarks are the property of their respective owners.



#### **ABSOLUTE MAXIMUM RATINGS(1)**

Supply Voltage	±18V
Input Voltage Range	
Differential Input Voltage	Total V <sub>S</sub> ±4V
Operating Temperature	$OM^{-1}$
P and U Packages	25°C to + 85°C
Storage Temperature	COMP
P and U Packages	40°C to +125°C
Output Short Circuit to Ground (T <sub>A</sub> = +25°C)	Continuous
Junction Temperature	+175°C
Lead Temperature	$\sim 100$
P Package (soldering, 10s)	+300°C
U Package, SOIC (3s)	+260°C
W. C . TW . W	117.

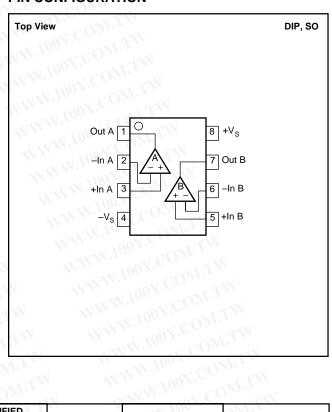
NOTE: Stresses above these ratings may cause permanent damage.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

#### PIN CONFIGURATION



#### **PACKAGE/ORDERING INFORMATION**

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR <sup>(1)</sup>	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
OPA2107	DIP-8	Р	-25°C to +85°C	OPA2107AP	OPA2107AP	Tube, 50
OPA2107	SO-8	N D WY	-25°C to +85°C	OPA2107AU "	OPA2107AU OPA2107AU/2K5	Tube, 100 Tape and Reel, 2500

WWW.100Y.COM

WWW.100Y.COM.TW 勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www. 100y. com. tw

WWW.100Y.COM.TW



### **ELECTRICAL CHARACTERISTICS**

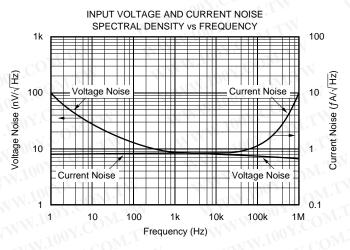
At  $T_A = +25$ °C,  $V_S = \pm 15$ V, unless otherwise noted.

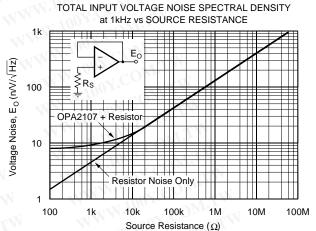
CONDITION	MIN	TYP	MAX	UNITS
	3.4 (40) 6.4	+	+	4
WWW. OW.	COL TAN		'	1
$V_{CM} = 0V$	WW.	0.1	1	mV
WW. JOHN	WT. TW	0.5	2	mV
W.L.	TOM.	3	10	μV/°C
$V_S = \pm 10 \text{ to } \pm 18V$	80	96	'	dB
Mr. XIWW.	COM		†	
$V_{CM} = 0V$	10 A OW.	4	10	pA
	"I CO"	0.25	1.5	nA
$V_{CM} = 0V$	100 r OM	1	8	pA
COM.	N.CU	TI	1	nA
-MITH	700	1.1	+ ''	+
$R_{0}=0$ $MM$	- Anoy.C	30	•	nV/√Hz
Ng - U	N. 100		,	nV/√Hz nV/√Hz
W.CO. TW WY	1001		·	
J. JOHN.	W In Co		·	nV/√Hz
WY.CO. TW	1007.0		·	nV/√ <del>Hz</del>
Mr. William	-101.100	1.2		μVp-p
LA COM TO	NT LOOK!	0.85	4	μVrms
100 r.	-10V.10V	1.2	-   - ·	fA/√ <del>Hz</del>
MY.CO TW	1003	23	1	fAp-p
The COMP	ALVINO.	COM	- 11	
1100x.	1 100	1013    2	'	Ω    pF
N. TW. COM. TW	WWW	1014    4	TW	Ω    pF
M:100	TINN. 10	<1 COMP	- N	
TY TY	±10.5	±11	TV	V
COM.			The second second	v
$V_{0M} = \pm 10V$	80	94	LITI	dB
CM CM		Tany.cu	The same of the sa	1
The state of the s	00	100 20	W.T.	1
$V_0 = \pm 10V$ , $R_L = 2k\Omega$		96	Pr TV	dB
N 1 100x M.I.	80	94	OWILL	dB
WWW. OUX.CO. TW	MAN	100X.	TIM	<u> </u>
G = +1	13	18	COM.	V/μs
G = -1, 10V Step	- N.A.	1.5	TI	μs
W. The COM.		2	COMP.	μs
G = 100	N N	4.5	1.0	MHz
			· COM.	%
	W V	120	17.0	dB
COM		TANN TO	COM	
M 100x.	$T_{A}$	+15	Mr. 201	V
- ALMIN W. CO.	+45	410	any .Co.	V
M 21 100 r. CON.	14.5	+45	100 -	mA
WWW. and Co.		14.0	Tanny.Co	110
	MP	VV	To C	DMr.
$R_L = 2k\Omega$			-100x-	V
CO.		±11.5	N.10	OWA
M. M. JOHN	±10	±40	1007.	mA
1MHz	·OM·	70	M.Iv	Ω
G = +1	WILL	1000	1 1007	pF
VOC. IN.	COM	W	M.M	.V.CU
11 M. M. 100	-25	4 -	+85	°C
THE WAY		1	- 4. B.   M. V.	°C
rith M. MI 100.		7		°C
Wr.	COM	- N	7120	NV.U
1. TW W' 10"	M.I.	00	NY WAY	OV POCAN
UM.	COn		-XIVI VI	°C/W
TW W'	101.	1/5	NY .	°C/W
COM. WWW.	~W.Co.	W	MM	- 00Y.
	$V_{S} = \pm 10 \text{ to } \pm 18V$ $V_{CM} = 0V$ $V_{CM} = 0V$ $R_{S} = 0$ $V_{CM} = \pm 10V$ $V_{O} = \pm 10V, R_{L} = 2k\Omega$ $G = +1$ $G = -1, 10V \text{ Step}$ $G = 100$ $G = +1, f = 1kHz$ $f = 100Hz, R_{L} = 2k\Omega$ $R_{L} = 2k\Omega$ $1MHz$ $G = +1$	$V_{S} = \pm 10 \text{ to} \pm 18V \qquad 80$ $V_{CM} = 0V$ $V_{CM} = 0V$ $R_{S} = 0$ $V_{CM} = \pm 10V \qquad 80$ $V_{O} = \pm 10V, R_{L} = 2k\Omega \qquad 82$ $80$ $G = +1 \qquad 13$ $G = -1, 10V \text{ Step}$ $G = 100$ $G = +1, f = 1kHz$ $f = 100Hz, R_{L} = 2k\Omega$ $\pm 4.5$ $R_{L} = 2k\Omega \qquad \pm 11$ $\pm 10.5$ $\pm 10$ $1MHz$ $G = +1$ $-25$ $-25$ $-40$	$V_{S} = \pm 10 \text{ to} \pm 18 \text{V} \qquad 80 \qquad 96 \qquad 3 \qquad 3 \qquad 96 \qquad 96 \qquad 4 \qquad 4 \qquad 0.25 \qquad 1 \qquad 4 \qquad 0.25 \qquad 1 \qquad $	$V_{S} = \pm 10 \text{ to} \pm 18 \text{V} \qquad 80 \qquad 96 \qquad 10 \qquad 1$

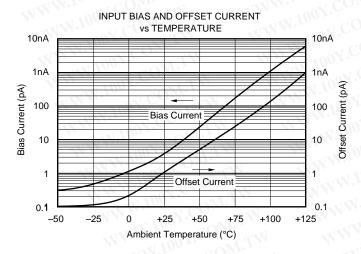


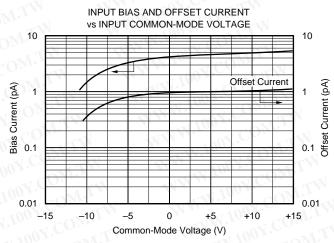
#### TYPICAL CHARACTERISTICS

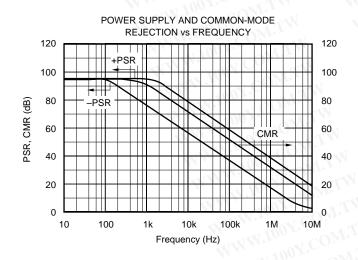
 $T_A = +25^{\circ}C$ ,  $V_S = \pm 15V$  unless otherwise noted.

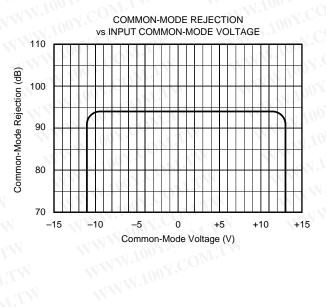






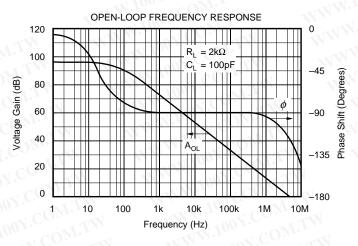


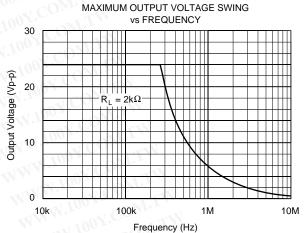


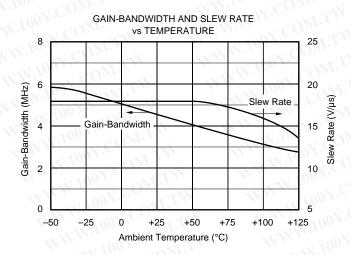


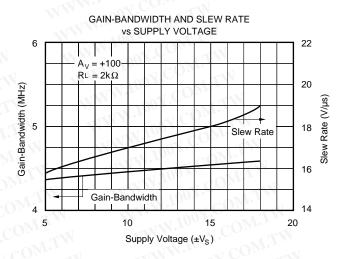
# **TYPICAL CHARACTERISTICS (Cont.)**

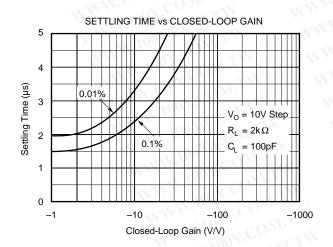
 $T_A = +25$ °C,  $V_S = \pm 15$ V unless otherwise noted.

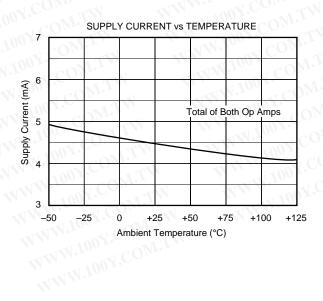








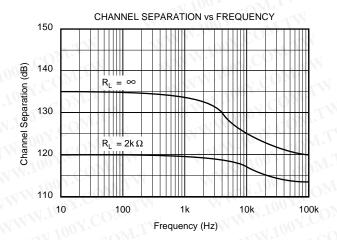


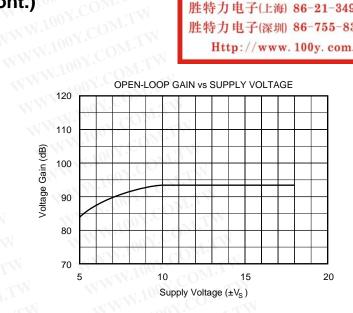


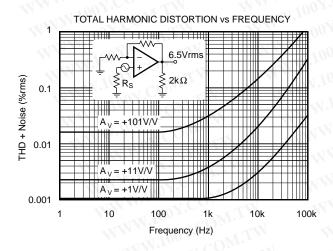


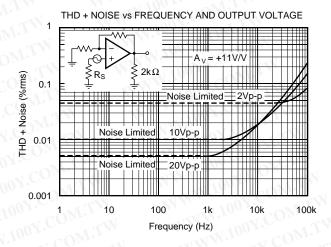
# TYPICAL CHARACTERISTICS (Cont.) T<sub>A</sub> = +25°C, V<sub>c</sub> = ±15V unless otherwise

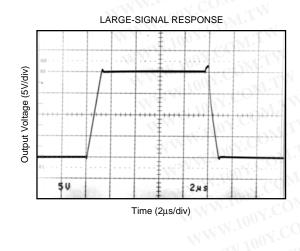
 $T_A = +25$ °C,  $V_S = \pm 15$ V unless otherwise noted.

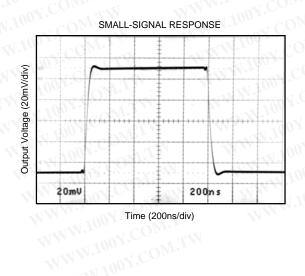












# APPLICATIONS INFORMATION AND CIRCUITS

The OPA2107 is unity-gain stable and has an excellent phase margin. This makes it easy to use in a wide variety of applications.

Power-supply connections should be bypassed with capacitors positioned close to the amplifier pins. In most cases,  $0.1\mu F$  ceramic capacitors are adequate. Applications with larger load currents and fast transient signals may need up to  $1\mu F$  tantalum bypass capacitors.

#### INPUT BIAS CURRENT

The OPA2107 **Difet** input stages have very low input bias current—an order of magnitude lower than BIFET op amps. Circuit-board leakage paths can significantly degrade performance. This is especially evident with the SO-8 surface-mount package where pin-to-pin dimensions are particularly small. Residual soldering flux, dirt, and oils, which conduct leakage current, can be removed by proper cleaning. In most instances, a two-step cleaning process is adequate using a clean organic solvent rinse followed by deionized water. Each rinse should be followed by a 30-minute bake at 85°C.

A circuit-board guard pattern effectively reduces errors due to circuit-board leakage (Figure 1). By encircling critical high-impedance nodes with a low-impedance connection at the same circuit potential, any leakage currents will flow harmlessly to the low-impedance node. Guard traces should be placed on all levels of a multiple-layer circuit board.

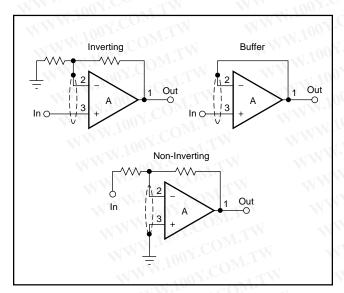


FIGURE 1. Connection of Input Guard.

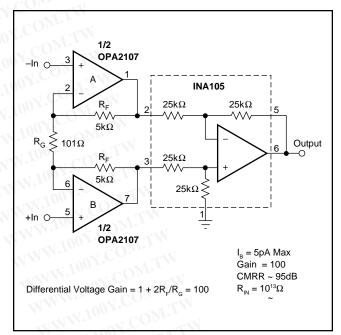


FIGURE 2. FET Input Instrumentation Amplifier.

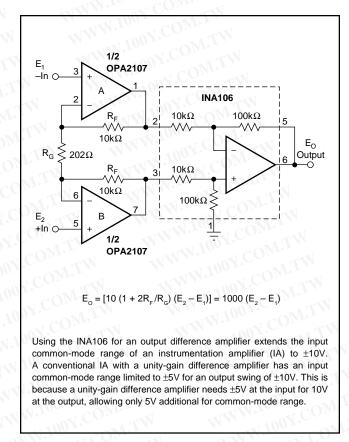


FIGURE 3. Precision Instrumentation Amplifier.





#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins I	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
OPA2107AP	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA2107APG4	ACTIVE	PDIP	TW P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA2107AU	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA2107AU/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA2107AU/2K5E4	ACTIVE	SOIC	O D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA2107AUE4	ACTIVE	SOIC	COLD	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

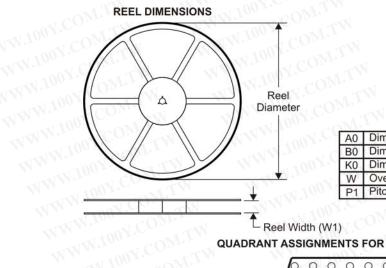
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

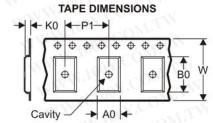
Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### PACKAGE MATERIALS INFORMATION

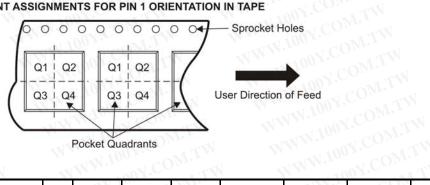
#### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



# W.100Y.COM.TW \*All dimensions are nominal

WWW.100Y.COM.TW

WWW.100Y.C

WWW.100Y.COM.T

WWW.100Y.COM.TW

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadran
OPA2107AU/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

WWW.100Y.COM.TW

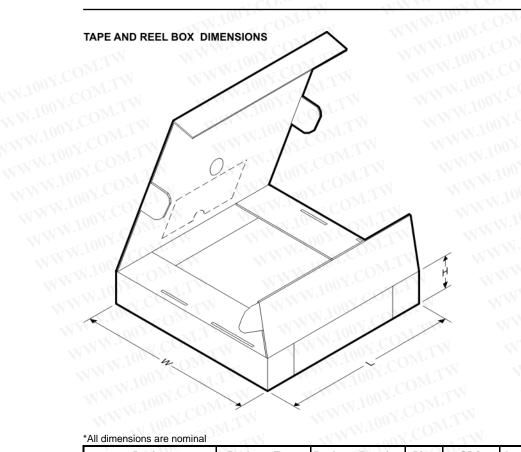
100Y.COM.TW

WWW.100Y.COM.TW

WWW.100Y.COM.TW

WWW.100Y.





WWW.100Y.CO

WWW.100Y.COM.TW

WWW.100Y.C

#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DPA2107AU/2K5	SOIC	D 11.100	8	2500	346.0	346.0	29.0

WWW.100Y.COM.TW WWW.100Y.COM.TW 勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787

WWW.100Y.COM.TW

noY.COM.TW

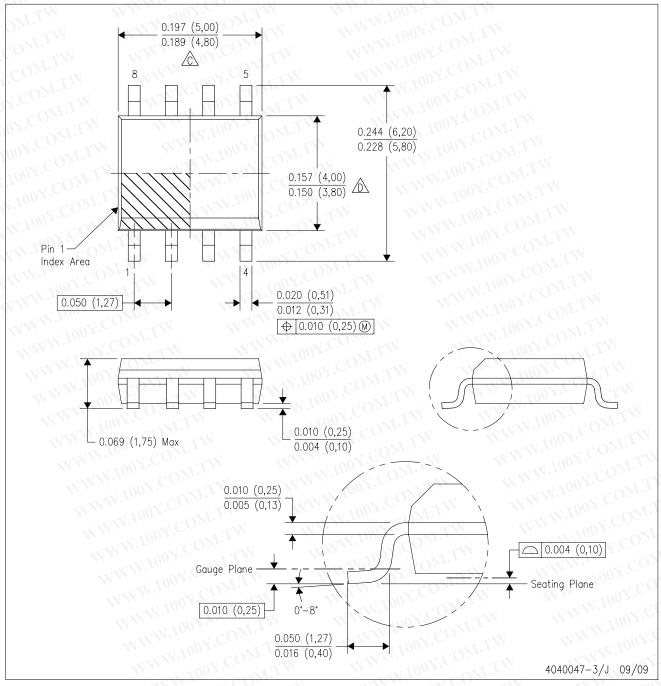
WWW.100Y.COM.TW

WWW.100Y.C

Http://www. 100y. com. tw

### D (R-PDSO-G8)

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

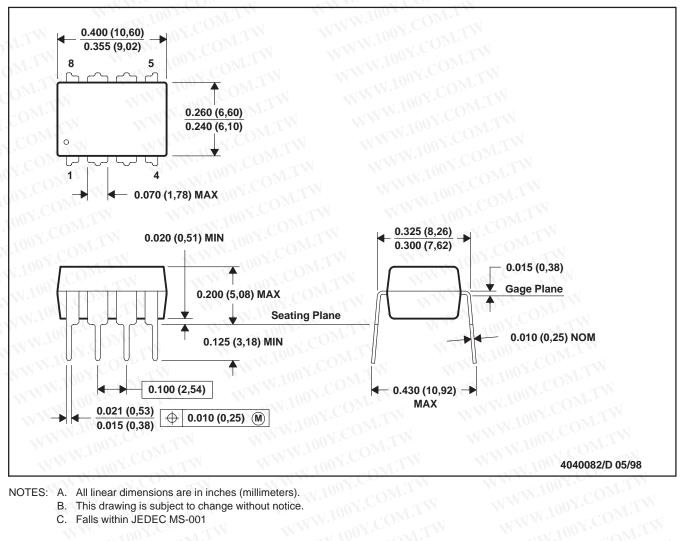
  Body width does not include interlead flash. Interlead flash at -11.

  E. Reference IEDEC No. 2019
- E. Reference JEDEC MS-012 variation AA.



#### P (R-PDIP-T8)

#### PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 WWW.100Y.COM.T

WWW.100Y.COM.TW WWW.100Y.COM.TW 特力材料886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www. 100y. com. tw

WWW.100Y.COM.TW

WWW.100Y.COM.TW

OOY.COM.TW